Freescale Semiconductor Inc

PART INFORMATION	
Mfg Item Number	MK30DN512ZVLK10
Mfg Item Name	LQFP 80 12*12*1.4P0.5

SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-11-28
Response Document ID	8263K50001S029A1.12
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION	
EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e3
EU RoHS Exemption(s)	

MANUFACTURING	
Mfg Item Number	MK30DN512ZVLK10
Mfg Item Name	LQFP 80 12*12*1.4P0.5
Version	ALL
Weight	0.491000
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Lead Frame Plating	0.0052						g					
Lead Frame Plating		Lead/Lead Compounds	Lead	7439-92-1		0.00000104	g	200	0.02		2	0.0002
Lead Frame Plating		Metals	Tin, metal	7440-31-5		0.00519896	g	999800	99.98		10588	1.0588
Epoxy Die Attach	0.0004						g					
Epoxy Die Attach		Solvents, additives, and other materials	Proprietary Material-Other acrylates	-		0.00005	g	125000	12.5		101	0.0101
Epoxy Die Attach		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.00001	g	25000	2.5		20	0.002
Epoxy Die Attach		Solvents, additives, and other materials	Other organic Silicon Compounds	-		0.000005	g	12500	1.25		10	0.001
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.000312	g	780000	78		635	0.0635
Epoxy Die Attach		Plastics/polymers	Proprietary Material-acrylonitrile/butadiene copolymer, carboxyl terminated	-		0.000023	g	57500	5.75		46	0.0046
Bonding Wire, Copper	0.0024						g					
Bonding Wire, Copper		Metals	Copper, metal	7440-50-8		0.002328	g	970000	97		4741	0.4741
Bonding Wire, Copper		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000072	g	30000	3		146	0.0146
Die Encapsulant, Halogen-free	0.4099						g					
Die Encapsulant, Halogen-free		Metals	Aluminum, metal	7429-90-5		0.00102639	g	2504	0.2504		2090	0.209
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.00369484	g	9014	0.9014		7525	0.7525
Die Encapsulant, Halogen-free		Metals	Magnesium, metal	7439-95-4		0.00307917	g	7512	0.7512		6271	0.6271
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Other organic phosphorous compounds	-		0.00205278	g	5008	0.5008		4180	0.418
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Silicone modified epoxy resin	218163-11-2		0.03777106	g	92147	9.2147		76926	7.6926
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Other organic Silicon Compounds	-		0.00164206	g	4006	0.4006		3344	0.3344
Die Encapsulant, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.3606337	g	879809	87.9809		734502	73.4502
Copper Lead Frame	0.0454						g					
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.04270151	g	940562	94.0562		86968	8.6968
Copper Lead Frame		Solvents, additives, and other materials	Silicon	7440-21-3		0.00032915	g	7250	0.725		670	0.067
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.00005675	g	1250	0.125		115	0.0115
Copper Lead Frame		Lead/Lead Compounds	Lead	7439-92-1		0.00001421	g	313	0.0313		28	0.0028
Copper Lead Frame		Metals	Magnesium, metal	7439-95-4		0.00007945	g	1750	0.175		161	0.0161
Copper Lead Frame		Metals	Manganese, metal	7439-96-5		0.00002838	g	625	0.0625		57	0.0057
Copper Lead Frame		Nickel (external applications only)	Nickel	7440-02-0		0.0014528	g	32000	3.2		2958	0.2958
Copper Lead Frame		Metals	Silver, metal	7440-22-4		0.000454	g	10000	1		924	0.0924
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.00028375	g	6250	0.625		577	0.0577
Silicon Semiconductor Die	0.0277						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000554	g	20000	2		1128	0.1128
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.027146	g	980000	98		55287	5.5287

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MK30DN512ZVLK10_IPC1752_v11.xml

http://www.freescale.com/mcds/MK30DN512ZVLK10_IPC1752A.xml